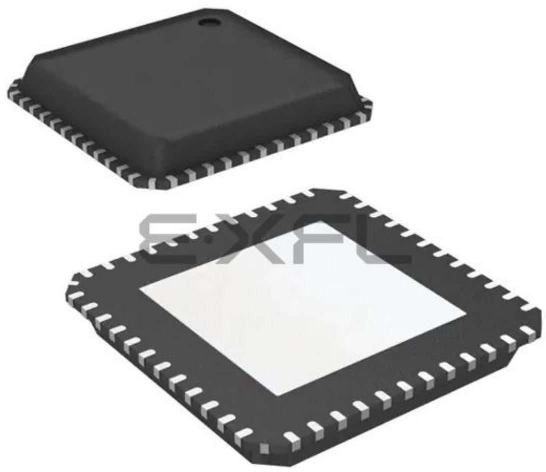

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	CANbus, I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I²S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	200KB (200K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-VFQFN Exposed Pad
Supplier Device Package	PG-VQFN-48-73
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1403q048x0200aaxuma1

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Features

CPU subsystem

- 32-bit ARM Cortex-M0 CPU Core
  - 0.84 DMIPS/MHz (Dhrystone 2.1) at 48 MHz
- Nested Vectored Interrupt Controller
- 64 interrupt nodes
- MATH coprocessor
  - 24-bit trigonometric calculation (CORDIC)
  - 32-bit divide operation
- 2x4 channels ERU for event interconnections

On-Chip Memories

- 8 Kbyte ROM
- 16 Kbyte SRAM (with parity)
- up to 200 Kbyte Flash (with ECC)

Supply, Reset and Clock

- 1.8 V to 5.5 V supply with power on reset and brownout detector
- On-chip clock monitor
- External crystal oscillator support (32 kHz and 4 to 20 MHz)
- Internal slow and fast oscillators without the need of PLL

System Control

- Window watchdog
- Real time clock module
- Pseudo random number generator

Communication Peripherals

- Four USIC channels, usable as
  - UART (up to 12 Mb/s)
  - single-SPI (up to 12 Mb/s)
  - double-SPI (up to 2 × 12 Mb/s)
  - quad-SPI (up to 4 × 12 Mb/s)
  - IIC (up to 400 kb/s)
  - IIS (up to 12 Mb/s)
  - LIN interfaces (20kb/s)
- LEDTS in Human-Machine interface
  - up to 24 touch pads
  - drive up to 144 LEDs
- MultiCAN+, Full-CAN/Basic-CAN with 2 nodes, 32 message objects (up to 1 MBaud)

Analog Frontend Peripherals

- A/D Converters (up to 12 analog inputs)
  - 2 sample and hold stages
  - fast 12-bit ADC (up to 1.1 MS/s), adjustable gain
  - 0 V to 5.5 V input range
- Up to 8 channels out of range comparators
- Up to 4 fast analog comparators
- Temperature Sensor

Industrial Control Peripherals

- 2x4 16-bit 96 MHz CCU4 timers for signal monitoring and PWM
- 2x4 16-bit 96 MHz CCU8 timers for complex PWM, complementary high/low side switches and multi phase control
- 2x POSIF for hall and quadrature encoders, motor positioning
- 9 channel BCCU (brightness and color control) for LED lighting applications

Up to 56 Input/Output Ports

- 1.8 V to 5.5 V capable
- up to 8 high current pads (50 mA sink)

On-Chip Debug Support

- 4 breakpoints, 2 watchpoints
- ARM serial wire debug, single-pin debug interfaces

Programming Support

- Single-pin bootloader
- Secure bootstrap loader SBSL (optional)

Packages

- TSSOP-38 (9.7 × 6.4 mm^2)
- VQFN-40/48/64 (5×5/7×7/8×8 mm^2)
- LQFP-64 (12 × 12 mm^2)

Tools

- Free DAVE™ toolchain with low level drivers and apps

Table 2 Synopsis of XMC1400 Device Types (cont'd)

Derivative	Package	Flash Kbytes
XMC1403-Q048X0200	PG-VQFN-48	200
XMC1403-Q064X0064	PG-VQFN-64	64
XMC1403-Q064X0128	PG-VQFN-64	128
XMC1403-Q064X0200	PG-VQFN-64	200
XMC1404-Q048X0064	PG-VQFN-48	64
XMC1404-Q048X0128	PG-VQFN-48	128
XMC1404-Q048X0200	PG-VQFN-48	200
XMC1404-Q064X0064	PG-VQFN-64	64
XMC1404-Q064X0128	PG-VQFN-64	128
XMC1404-Q064X0200	PG-VQFN-64	200
XMC1404-F064X0064	PG-LQFP-64	64
XMC1404-F064X0128	PG-LQFP-64	128
XMC1404-F064X0200	PG-LQFP-64	200

2.2.1 Package Pin Summary

The following general building block is used to describe each pin:

Table 4 Package Pin Mapping Description

Function	Package A	Package B	...	Pad Type
Px.y	N	N		Pad Class

The table is sorted by the "Function" column, starting with the regular Port pins (Px.y), followed by the supply pins.

The following columns, titled with the supported package variants, lists the package pin number to which the respective function is mapped in that package.

The "Pad Type" indicates the employed pad type:

- STD_INOUT (standard bi-directional pads)
- STD_INOUT/AN (standard bi-directional pads with analog input)
- STD_INOUT/clock (standard bi-directional pads with oscillator function)
- High Current (high current bi-directional pads)
- STD_IN/AN (standard input pads with analog input)
- Power (power supply)

Details about the pad properties are defined in the Electrical Parameter chapter.

Table 5 Package Pin Mapping

Function	LQFP 64, VQFN 64	VQFN 48	VQFN 40	TSSOP 38	Pad Type	Notes
P0.0	41	29	23	17	STD_INOUT	
P0.1	42	30	24	18	STD_INOUT	
P0.2	43	31	25	19	STD_INOUT	
P0.3	44	32	26	20	STD_INOUT	
P0.4	45	33	27	21	STD_INOUT	
P0.5	46	34	28	22	STD_INOUT	
P0.6	47	35	29	23	STD_INOUT	
P0.7	48	36	30	24	STD_INOUT	
P0.8/ RTC_ XTAL1	51	39	33	27	STD_INOUT /clock_IN	

2.2.4 Hardware Controlled I/O Function Description

The following general building block is used to describe the hardware I/O and pull control functions of each PORT pin:

Table 8 Hardware Controlled I/O Function Description

Function	Outputs	Inputs	Pull Control	
	HWO0	**HWI0**	**HW0_PD**	**HW0_PU**
P0.0	MODB.OUT	MODB.INA		
Pn.y			$\overline{\text{MODC.OUT}}$	MODC.OUT

By Pn_HWSEL, it is possible to select between different hardware "masters" (HWO0/HWI0, HWO1/HWI1). The selected peripheral can take control of the pin(s). Hardware control overrules settings in the respective port pin registers. Additional hardware signals HW0_PD/HW1_PD and HW0_PU/HW1_PU controlled by the peripherals can be used to control the pull devices of the pin.

Please refer to the **Hardware Controlled I/O Functions** table for the complete hardware I/O and pull control function mapping.

Port I/O Function Table

Table 9 Port I/O Functions

Function	Outputs									Inputs											
	ALT1	**ALT2**	**ALT3**	**ALT4**	**ALT5**	**ALT6**	**ALT7**	**ALT8**	**ALT9**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**
P0.0	ERU0.PDOUT0	LEDTS0.LINE7	ERU0.GOUT0	CCU40.OUT0	CCU80.OUT00	USIC0_CH0.SELO0	USIC0_CH1.SELO0	CCU81.OUT00	USIC1_CH1.DOUT0	BCCU0.TRAPINB	CCU40.IN0AC					USIC1_CH1.DX0A	USIC0_CH0.DX2A		USIC0_CH1.DX2A		
P0.1	ERU0.PDOUT1	LEDTS0.LINE6	ERU0.GOUT1	CCU40.OUT1	CCU80.OUT01	BCCU0.OUT8	SCU.VDROP	USIC1_CH1.SCLKOUT	USIC1_CH1.DOUT0		CCU40.IN1AC					USIC1_CH1.DX0B	USIC1_CH1.DX1A				
P0.2	ERU0.PDOUT2	LEDTS0.LINE5	ERU0.GOUT2	CCU40.OUT2	CCU80.OUT02	VADC0.EMUX02	CCU80.OUT10	USIC1_CH0.SCLKOUT	USIC1_CH0.DOUT0		CCU40.IN2AC					USIC1_CH0.DX0A	USIC1_CH0.DX1A				
P0.3	ERU0.PDOUT3	LEDTS0.LINE4	ERU0.GOUT3	CCU40.OUT3	CCU80.OUT03	VADC0.EMUX01	CCU80.OUT11	USIC1_CH1.SCLKOUT	USIC1_CH0.DOUT0		CCU40.IN3AC					USIC1_CH0.DX0B					
P0.4	BCCU0.OUT0	LEDTS0.LINE3	LEDTS0.COL3	CCU40.OUT1	CCU80.OUT13	VADC0.EMUX00	WWDT.SERVICE_OUT	USIC1_CH1.SELO0	CAN.N0_TXD			CCU41.IN0AB	CCU80.IN0AB							CAN.N0_RXDA	
P0.5	BCCU0.OUT1	LEDTS0.LINE2	LEDTS0.COL2	CCU40.OUT0	CCU80.OUT12	ACMP2.OUT	CCU80.OUT01	VADC0.EMUX10	CAN.N0_TXD			CCU41.IN1AB	CCU80.IN1AB							CAN.N0_RXDB	
P0.6	BCCU0.OUT2	LEDTS0.LINE1	LEDTS0.COL1	CCU40.OUT0	CCU80.OUT11	USIC0_CH1.MCLKOUT	USIC0_CH1.DOUT0	VADC0.EMUX11	CCU41.OUT0		CCU40.IN0AB	CCU41.IN2AB						USIC0_CH1.DX0C			
P0.7	BCCU0.OUT3	LEDTS0.LINE0	LEDTS0.COL0	CCU40.OUT1	CCU80.OUT10	USIC0_CH0.SCLKOUT	USIC0_CH1.DOUT0	VADC0.EMUX12	CCU41.OUT1		CCU40.IN1AB	CCU41.IN3AB					USIC0_CH0.DX1C	USIC0_CH1.DX0D	USIC0_CH1.DX1C		
P0.8/ RTC_XTAL1	BCCU0.OUT4	LEDTS1.LINE0	LEDTS0.COLA	CCU40.OUT2	CCU80.OUT20	USIC0_CH0.SCLKOUT	USIC0_CH1.SCLKOUT	CCU81.OUT20	CCU41.OUT2		CCU40.IN2AB						USIC0_CH0.DX1B		USIC0_CH1.DX1B		
P0.9/ RTC_XTAL2	BCCU0.OUT5	LEDTS1.LINE1	LEDTS0.COL6	CCU40.OUT3	CCU80.OUT21	USIC0_CH0.SELO0	USIC0_CH1.SELO0	CCU81.OUT21	CCU41.OUT3		CCU40.IN3AB						USIC0_CH0.DX2B		USIC0_CH1.DX2B		
P0.10/ XTAL1	BCCU0.OUT6	LEDTS1.LINE2	LEDTS0.COL5	ACMP0.OUT	CCU80.OUT22	USIC0_CH0.SELO1	USIC0_CH1.SELO1	CCU81.OUT22					CCU80.IN2AB	CCU81.IN2AB			USIC0_CH0.DX2C		USIC0_CH1.DX2C		
P0.11/ XTAL2	BCCU0.OUT7	LEDTS1.LINE3	LEDTS0.COL4	USIC0_CH0.MCLKOUT	CCU80.OUT23	USIC0_CH0.SELO2	USIC0_CH1.SELO2	CCU81.OUT23									USIC0_CH0.DX2D		USIC0_CH1.DX2D		
P0.12	BCCU0.OUT6	LEDTS1.LINE4	LEDTS0.COL3	LEDTS1.COL3	CCU80.OUT33	USIC0_CH0.SELO3	CCU80.OUT20		CAN.N1_TXD	BCCU0.TRAPINA	CCU40.IN0AA	CCU40.IN1AA	CCU40.IN2AA	CCU81.IN0AU	CCU40.IN3AA	CCU80.IN0AA	USIC0_CH0.DX2E	CCU80.IN1AA	CCU80.IN2AA	CAN.N1_RXDA	CCU80.IN3AA

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs											
	ALT1	**ALT2**	**ALT3**	**ALT4**	**ALT5**	**ALT6**	**ALT7**	**ALT8**	**ALT9**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**
P0.13	WWDT.SERVICE_OUT	LEDTS1.LINE5	LEDTS0.COL2	LEDTS1.COL2	CCU80.OUT32	USIC0_CH0.SELO4	CCU80.OUT21		CAN.N1_TXD				CCU80.IN3AB	CCU81.IN1AU	POSIF0.IN0B		USIC0_CH0.DX2F			CAN.N1_RXDB	
P0.14	BCCU0.OUT7	LEDTS1.LINE6	LEDTS0.COL1	LEDTS1.COL1	CCU80.OUT31	USIC0_CH0.DOUT0	USIC0_CH0.SCLKOUT		CAN.N0_TXD					CCU81.IN2AU	POSIF0.IN1B	USIC0_CH0.DX0A	USIC0_CH0.DX1A	USIC1_CH1.DX5B		CAN.N0_RXDC	
P0.15	BCCU0.OUT8	LEDTS1.LINE7	LEDTS0.COL0	LEDTS1.COL0	CCU80.OUT30	USIC0_CH0.DOUT0	USIC0_CH1.MCLKOUT		CAN.N0_TXD					CCU81.IN3AU	POSIF0.IN2B	USIC0_CH0.DX0B		USIC1_CH1.DX3B	USIC1_CH1.DX4B	CAN.N0_RXDD	
P1.0	BCCU0.OUT0	CCU40.OUT0	LEDTS0.COL0	LEDTS1.COLA	CCU80.OUT00	ACMP1.OUT	USIC0_CH0.DOUT0	CCU81.OUT00	CAN.N0_TXD						POSIF0.IN2A	USIC0_CH0.DX0C				CAN.N0_RXDG	
P1.1	ERU1.PDOUT1	CCU40.OUT1	LEDTS0.COL1	LEDTS1.COL0	CCU80.OUT01	USIC0_CH0.DOUT0	USIC0_CH1.SELO0	CCU81.OUT01	CAN.N0_TXD						POSIF0.IN1A	USIC0_CH0.DX0D	USIC0_CH0.DX1D		USIC0_CH1.DX2E	CAN.N0_RXDH	
P1.2	ERU1.PDOUT2	CCU40.OUT2	LEDTS0.COL2	LEDTS1.COL1	CCU80.OUT10	ACMP2.OUT	USIC0_CH1.DOUT0	CCU81.OUT10	CAN.N1_TXD						POSIF0.IN0A			USIC0_CH1.DX0B		CAN.N1_RXDG	
P1.3	ERU1.PDOUT3	CCU40.OUT3	LEDTS0.COL3	LEDTS1.COL2	CCU80.OUT11	USIC0_CH1.SCLKOUT	USIC0_CH1.DOUT0	CCU81.OUT11	CAN.N1_TXD									USIC0_CH1.DX0A	USIC0_CH1.DX1A	CAN.N1_RXDH	
P1.4	ERU1.PDOUT0	USIC0_CH1.SCLKOUT	LEDTS0.COL4	LEDTS1.COL3	CCU80.OUT20	USIC0_CH0.SELO0	USIC0_CH1.SELO1	CCU81.OUT20	CCU41.OUT0							USIC0_CH0.DX5E		USIC0_CH1.DX5E			
P1.5	ERU1.PDOUT1	USIC0_CH0.DOUT0	LEDTS0.COLA	BCCU0.OUT1	CCU80.OUT21	USIC0_CH0.SELO1	USIC0_CH1.SELO2	CCU81.OUT21	CCU41.OUT1									USIC0_CH1.DX5F			
P1.6	ERU1.PDOUT2	USIC0_CH1.DOUT0	LEDTS0.COL5	USIC0_CH0.SCLKOUT	BCCU0.OUT2	USIC0_CH0.SELO2	USIC0_CH1.SELO3	CCU81.OUT30	CCU41.OUT2						POSIF1.IN2A	USIC0_CH0.DX5F					
P1.7	BCCU0.OUT8	CCU40.OUT3	LEDTS0.COL6	LEDTS1.COL4		ACMP3.OUT	ERU1.PDOUT3	CCU81.OUT31	CCU41.OUT3						POSIF1.IN1A	USIC1_CH0.DX5B			USIC1_CH1.DX2C		
P1.8	BCCU0.OUT0	CCU40.OUT0	USIC1_CH1.SCLKOUT	VADC0.EMUX02		ACMP1.OUT	ERU1.PDOUT0	CCU81.OUT32							POSIF1.IN0A	USIC1_CH0.DX3B	USIC1_CH0.DX4B		USIC1_CH1.DX1C		
P2.0	ERU0.PDOUT3	CCU40.OUT0	ERU0.GOUT3	LEDTS1.COL5	CCU80.OUT20	USIC0_CH0.DOUT0	USIC0_CH0.SCLKOUT	CCU81.OUT20	CAN.N0_TXD		VADC0.G0CH5					USIC0_CH0.DX0E	USIC0_CH0.DX1E		USIC0_CH1.DX2F	CAN.N0_RXDE	ERU0.0B0
P2.1	ERU0.PDOUT2	CCU40.OUT1	ERU0.GOUT2	LEDTS1.COL6	CCU80.OUT21	USIC0_CH0.DOUT0	USIC0_CH1.SCLKOUT	CCU81.OUT21	CAN.N0_TXD	ACMP2.INP	VADC0.G0CH6					USIC0_CH0.DX0F		USIC0_CH1.DX3A	USIC0_CH1.DX4A	CAN.N0_RXDF	ERU0.1B0

Table 10 Hardware I/O Controlled Functions

Function	Outputs	Outputs	Inputs	Inputs	Pull Control	Pull Control	Pull Control	Pull Control
	HWO0	HWO1	HWI0	HWI1	HW0_PD	HW0_PU	HW1_PD	HW1_PU
P1.3		USIC0_CH0.DOUT3		USIC0_CH0.HWIN3	$\overline{\text{BCCU0.OUT5}}$	BCCU0.OUT5		
P1.4					$\overline{\text{BCCU0.OUT6}}$	BCCU0.OUT6		
P1.5					$\overline{\text{BCCU0.OUT7}}$	BCCU0.OUT7		
P1.6					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8		
P1.7								
P1.8								
P2.0					$\overline{\text{BCCU0.OUT1}}$	BCCU0.OUT1		
P2.1					$\overline{\text{BCCU0.OUT6}}$	BCCU0.OUT6		
P2.2					$\overline{\text{BCCU0.OUT0}}$	BCCU0.OUT0	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.3					$\overline{\text{ACMP2.OUT}}$	ACMP2.OUT		
P2.4					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8		
P2.5					$\overline{\text{ACMP1.OUT}}$	ACMP1.OUT		
P2.6					$\overline{\text{BCCU0.OUT2}}$	BCCU0.OUT2	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.7					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.8					$\overline{\text{BCCU0.OUT1}}$	BCCU0.OUT1	$\overline{\text{CCU40.OUT2}}$	CCU40.OUT2
P2.9					$\overline{\text{BCCU0.OUT7}}$	BCCU0.OUT7	$\overline{\text{CCU40.OUT2}}$	CCU40.OUT2
P2.10					$\overline{\text{BCCU0.OUT4}}$	BCCU0.OUT4		
P2.11					$\overline{\text{BCCU0.OUT5}}$	BCCU0.OUT5		
P2.12					$\overline{\text{BCCU0.OUT3}}$	BCCU0.OUT3	$\overline{\text{CCU41.OUT0}}$	CCU41.OUT0
P2.13					$\overline{\text{BCCU0.OUT4}}$	BCCU0.OUT4	$\overline{\text{CCU41.OUT2}}$	CCU41.OUT2
P3.0								
P3.1		USIC1_CH0.DOUT3		USIC1_CH0.HWIN3				
P3.2		USIC1_CH0.DOUT2		USIC1_CH0.HWIN2				
P3.3		USIC1_CH0.DOUT1		USIC1_CH0.HWIN1				
P3.4		USIC1_CH0.DOUT0		USIC1_CH0.HWIN0				
P4.0								
P4.1								
P4.2								
P4.3								

3.1.4 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the XMC1400. All parameters specified in the following tables refer to these operating conditions, unless noted otherwise.

Table 15 Operating Conditions Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Ambient Temperature	T_A	SR	-40	–	85	°C	Temp. Range F
			-40	–	105	°C	Temp. Range X
Digital supply voltage[1]	V_{DDP}	SR	1.8	–	5.5	V	
Short circuit current of digital outputs	I_{SC}	SR	-5	–	5	mA	
Absolute sum of short circuit currents of the device	ΣI_{SC_D}	SR	–	–	25	mA	

1) See also the Supply Monitoring thresholds, **Chapter 3.3.2**.

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Input low voltage on port pins (Large Hysteresis)	V_{ILPL}	SR	–	$0.08 \times V_{DDP}$	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Input high voltage on port pins (Large Hysteresis)	V_{IHPL}	SR	$0.85 \times V_{DDP}$	–	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Rise/fall time on High Current Pad[1]	t_{HCPR}, t_{HCPF}	CC	–	9	ns	50 pF @ 5 V[2]
			–	12	ns	50 pF @ 3.3 V[3]
			–	25	ns	50 pF @ 1.8 V[4]
Rise/fall time on Standard Pad[1]	t_R, t_F	CC	–	12	ns	50 pF @ 5 V[5]
			–	15	ns	50 pF @ 3.3 V[6].
			–	31	ns	50 pF @ 1.8 V[7].
Input Hysteresis on port pin except P2.3 - P2.9[8]	HYS	CC	$0.08 \times V_{DDP}$	–	V	CMOS Mode (5 V), Standard Hysteresis
			$0.03 \times V_{DDP}$	–	V	CMOS Mode (3.3 V), Standard Hysteresis
			$0.02 \times V_{DDP}$	–	V	CMOS Mode (2.2 V), Standard Hysteresis
			$0.5 \times V_{DDP}$	$0.75 \times V_{DDP}$	V	CMOS Mode(5 V), Large Hysteresis
			$0.4 \times V_{DDP}$	$0.75 \times V_{DDP}$	V	CMOS Mode(3.3 V), Large Hysteresis
			$0.2 \times V_{DDP}$	$0.65 \times V_{DDP}$	V	CMOS Mode(2.2 V), Large Hysteresis

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Maximum current into V_{DDP} (VQFN64, LQFP64)	I_{MVDD1}	SR	–	520	mA	
Maximum current into V_{DDP} (VQFN48)	I_{MVDD2}	SR	–	390	mA	
Maximum current into V_{DDP} (VQFN40)	I_{MVDD3}	SR	–	260	mA	
Maximum current out of V_{SS} (VQFN64, LQFP64)	I_{MVSS1}	SR	–	390	mA	
Maximum current out of V_{SS} (VQFN48)	I_{MVSS2}	SR	–	260	mA	
Maximum current out of V_{SS} (VQFN40)	I_{MVSS3}	SR	–	260	mA	

1) Rise/Fall time parameters are taken with 10% - 90% of supply.
2) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.150 ns/pF at 5 V supply voltage.
3) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.205 ns/pF at 3.3 V supply voltage.
4) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.445 ns/pF at 1.8 V supply voltage.
5) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.225 ns/pF at 5 V supply voltage.
6) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.288 ns/pF at 3.3 V supply voltage.
7) Additional rise/fall time valid for C_L = 50 pF - C_L = 100 pF @ 0.588 ns/pF at 1.8 V supply voltage.
8) Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.
9) An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin.
10) However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when V_{DDP} is powered off.

Table 17 ADC Characteristics (Operating Conditions apply)[1] (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Maximum sample rate in 8-bit mode[4]	f_{C8} CC	–	–	f_{ADC} / 38.5	–	1 sample pending
		–	–	f_{ADC} / 54.5	–	2 samples pending
RMS noise[5]	EN_{RMS} CC	–	1.5	–	LSB 12	DC input, SHSCFG.AREF = 00_B, GNCTRxz.GAINy = 00_B (unity gain), V_{DD} = 5.0 V, V_{AIN} = 2.5 V, 25°C
DNL error	EA_{DNL} CC	–	±2.0	–	LSB 12	
INL error	EA_{INL} CC	–	±4.0	–	LSB 12	
Gain error with external reference	EA_{GAIN} CC	–	±0.5	–	%	SHSCFG.AREF = 00_B (calibrated)
Gain error with internal reference[6]	EA_{GAIN} CC	–	±3.6	–	%	SHSCFG.AREF = $1X_B$ (calibrated), -40°C - 110°C
		–	±2.0	–	%	SHSCFG.AREF = $1X_B$ (calibrated), 0°C - 85°C
Offset error	EA_{OFF} CC	–	±8.0	–	mV	Calibrated, V_{DD} = 5.0 V

1) The parameters are defined for ADC clock frequencies f_{SH} = 32 MHz for the full supply range, and f_{SH} = 48 MHz at V_{DD_int}, V_{DD_ext} = 5 V. Usage of any other frequencies may affect the ADC performance.

2) The alternate reference ground connection is separate for each converter. This mode, therefore, provides the lowest noise impact.

3) No pending samples assumed, excluding sampling time and calibration.

4) Includes synchronization and calibration (average of gain and offset calibration).

5) This parameter can also be defined as an SNR value: SNR[dB] = 20 × log(A_{MAXeff} / N_{RMS}).
With A_{MAXeff} = 2^N / 2, SNR[dB] = 20 × log (2048 / N_{RMS}) [N = 12].
N_{RMS} = 1.5 LSB12, therefore, equals SNR = 20 × log (2048 / 1.5) = 62.7 dB.

6) Includes error from the reference voltage.

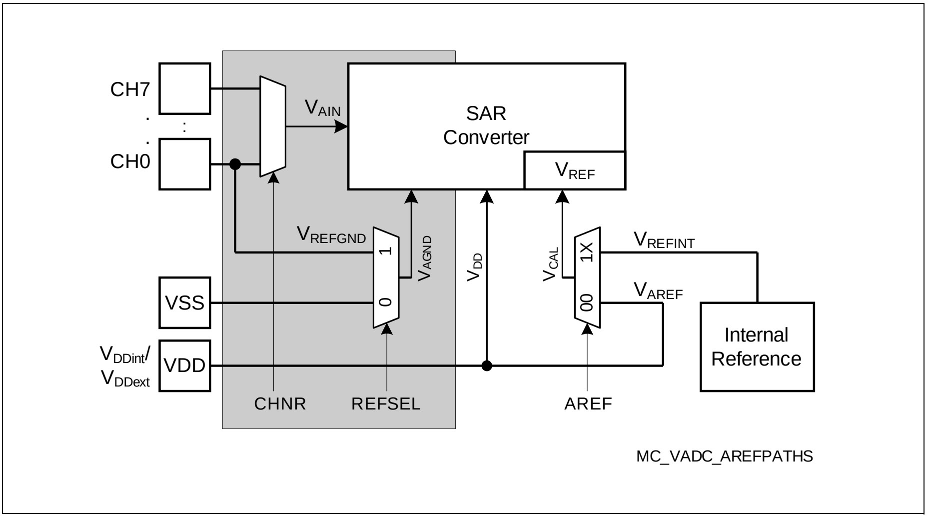

Figure 12 ADC Voltage Supply

Table 22 RTC_XTAL Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input frequency	f_{OSC} SR	–	32.768	–	kHz	
Oscillator start-up time[1)2)]	t_{OSCS} CC	–	–	5	s	
Input voltage at RTC_XTAL1	V_{IX} SR	-0.3	–	1.5	V	
Input amplitude (peak-to-peak) at RTC_XTAL1[2)3)]	V_{PPX} SR	0.2	–	1.2	V	

1) t_{OSCS} is defined from the moment the oscillator is enabled by the user with SCU_ANAOSCLPCTRL.MODE until the oscillations reach an amplitude at RTC_XTAL1 of 0.9 * V_{PPX}.

2) The external oscillator circuitry must be optimized by the customer and checked for negative resistance and amplitude as recommended and specified by crystal suppliers.

3) If the shaper unit is enabled and not bypassed.

3.2.7 Power Supply Current

The total power supply current defined below consists of a leakage and a switching component.

Application relevant values are typically lower than those given in the following tables, and depend on the customer's system operating conditions (e.g. thermal connection or used application configurations).

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 23 Power Supply parameter table; V_{DDP} = 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.[1]	Max.		
Active mode current Peripherals enabled f_{MCLK} / f_{PCLK} in MHz[2]	I_{DDPAE} CC	–	14.1	20	mA	48 / 96
		–	9.8	–	mA	24 / 48
		–	7.8	–	mA	16 / 32
		–	6.4	–	mA	8 / 16
		–	4.4	–	mA	1 / 1
Active mode current Peripherals disabled f_{MCLK} / f_{PCLK} in MHz[3]	I_{DDPAD} CC	–	6.2		mA	48 / 96
		–	4.6	–	mA	24 / 48
		–	3.6	–	mA	16 / 32
		–	3.1	–	mA	8 / 16
		–	1.8	–	mA	1 / 1
Active mode current Code execution from RAM Flash is powered down f_{MCLK} / f_{PCLK} in MHz	I_{DDPAR} CC	–	9.6	–	mA	48 / 96
Sleep mode current Peripherals clock enabled f_{MCLK} / f_{PCLK} in MHz[4]	I_{DDPSE} CC	–	11.0	–	mA	48 / 96
		–	7.6	–	mA	24 / 48
		–	6.4	–	mA	16 / 32
		–	5.3	–	mA	8 / 16
		–	4.2	–	mA	1 / 1

Table 23 Power Supply parameter table; V_{DDP} = 5V

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.[1]	Max.		
Sleep mode current Peripherals clock disabled Flash active f_{MCLK} / f_{PCLK} in MHz[5]	I_{DDPSD} CC	–	2.8	–	mA	48 / 96
		–	2.2	–	mA	24 / 48
		–	2.0	–	mA	16 / 32
		–	1.9	–	mA	8 / 16
		–	1.7	–	mA	1 / 1
Sleep mode current Peripherals clock disabled Flash powered down f_{MCLK} / f_{PCLK} in MHz[6]	I_{DDPSR} CC	–	2.2	–	mA	48 / 96
		–	1.7	–	mA	24 / 48
		–	1.4	–	mA	16 / 32
		–	1.2	–	mA	8 / 16
		–	1.1	–	mA	1 / 1
Deep Sleep mode current[7]	I_{DDPDS} CC	–	0.27	–	mA	
Wake-up time from Sleep to Active mode[8]	t_{SSA} CC	–	6	–	cycles	
Wake-up time from Deep Sleep to Active mode[9]	t_{DSA} CC	–	290	–	µsec	

1) The typical values are measured at T_A = + 25 °C and V_{DDP} = 5 V.
2) CPU and all peripherals clock enabled, Flash is in active mode.
3) CPU enabled, all peripherals clock disabled, Flash is in active mode.
4) CPU in sleep, all peripherals clock enabled and Flash is in active mode.
5) CPU in sleep, Flash is in active mode.
6) CPU in sleep, Flash is powered down and code executed from RAM after wake-up.
7) CPU in sleep, peripherals clock disabled, Flash is powered down and code executed from RAM after wake-up.
8) CPU in sleep, Flash is in active mode during sleep mode.
9) CPU in sleep, Flash is in powered down mode during deep sleep mode.

3.2.8 Flash Memory Parameters

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 25 Flash Memory Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Erase time per page / sector	t_{ERASE} CC	6.8	7.1	7.6	ms	
Program time per block	t_{PSER} CC	102	152	204	µs	
Wake-Up time	t_{WU} CC	–	32.2	–	µs	
Read time per word	t_a CC	–	50	–	ns	
Data Retention Time	t_{RET} CC	10	–	–	years	Max. 100 erase / program cycles
Flash Wait States [1)	$N_{WSFLASH}$ CC	0	0	0		f_{MCLK} = 8 MHz
		0	1	1		f_{MCLK} = 16 MHz
		1	2	2		f_{MCLK} = 32 MHz
		2	2	3		f_{MCLK} = 48 MHz
Erase Cycles	N_{ECYC} CC	–	–	$5*10^4$	cycles	Sum of page and sector erase cycles
Total Erase Cycles	N_{TECYC} CC	–	–	$2*10^6$	cycles	

1) Flash wait states are automatically inserted by the Flash module during memory read when needed. Typical values are calculated from the execution of the Dhrystone benchmark program.

3.3.3 On-Chip Oscillator Characteristics

Table 27 provides the characteristics of the 96 MHz digital controlled oscillator DCO1.

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 27 96 MHz DCO1 Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			Min.	Typ.	Max.		
Nominal frequency	f_{NOM}	CC	–	96	–	MHz	under nominal conditions[1] after trimming
Accuracy with adjustment based on XTAL as reference	Δf_{LTX}	CC	-0.3	–	0.3	%	with respect to f_{NOM}(typ), over temperature (-40 °C to 105 °C)
Accuracy	Δf_{LT}	CC	-1.7	–	3.4	%	with respect to f_{NOM}(typ), over temperature (0 °C to 85 °C)
			-3.9	–	4.0	%	with respect to f_{NOM}(typ), over temperature (-40 °C to 105 °C)

1) The deviation is relative to the factory trimmed frequency at nominal V_{DDC} and T_A = + 25 °C.

Table 28 provides the characteristics of the 32 kHz digital controlled oscillator DCO2.

Table 28 32 kHz DCO2 Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			Min.	Typ.	Max.		
Nominal frequency	f_{NOM}	CC	–	32.75	–	kHz	under nominal conditions[1] after trimming
Accuracy	Δf_{LT}	CC	-1.7	–	3.4	%	with respect to f_{NOM}(typ), over temperature (0 °C to 85 °C)
			-3.9	–	4.0	%	with respect to f_{NOM}(typ), over temperature (-40 °C to 105 °C)[1]

1) The deviation is relative to the factory trimmed frequency at nominal V_{DDC} and T_A = + 25 °C.

4.2 Package Outlines

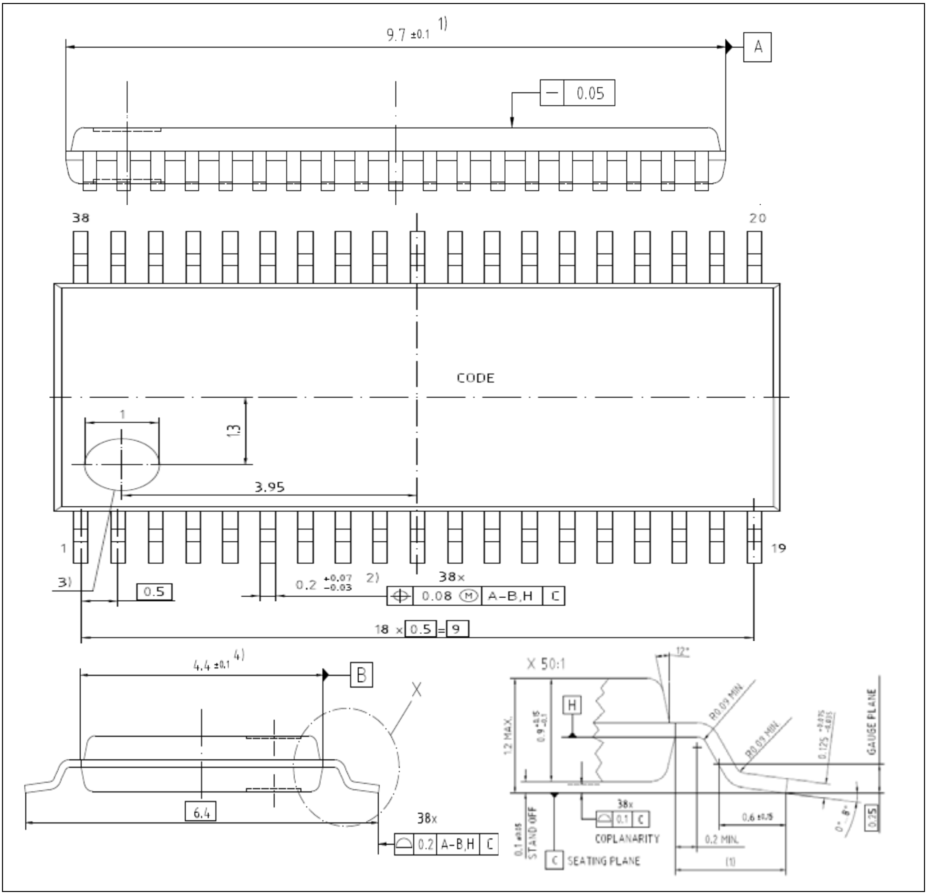

Figure 29 PG-TSSOP-38-9

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